

L Number	Hits	Search Text	DB	Time stamp
1	4693	((chip near sized near package) (chip near scale near package) csp)) not (flipchip (flip near chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/24 09:50
2	5816	((chip near sized near package) (chip near scale\$1 near package) csp)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/24 09:50
3	387	((chip near sized near package) (chip near scale\$1 near package) csp)) and (dissipat\$3 (heat near sink)) and (hole opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/24 09:51
4	5816	((chip near sized near package) (chip near scale\$1 near package) csp))(((chip near sized near package) (chip near scale near package) csp)) not (flipchip (flip near chip))) ((chip near sized near package) (chip near scale\$1 near package) csp)) and (dissipat\$3 (heat near sink)) and (hole opening via)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/24 09:52
5	5816	((chip near sized near package) (chip near scale near package) csp)) not (flipchip (flip near chip))) (((chip near sized near package) (chip near scale\$1 near package) csp))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/24 09:52
6	256	(((((chip near sized near package) (chip near scale near package) csp)) not (flipchip (flip near chip))) (((chip near sized near package) (chip near scale\$1 near package) csp))) and (heat near1 dissipat\$3) and (via vias hole opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/24 09:54
7	149	(((((chip near sized near package) (chip near scale near package) csp)) not (flipchip (flip near chip))) (((chip near sized near package) (chip near scale\$1 near package) csp))) and (heat near1 dissipat\$3) and (via vias hole opening)) and (electrode (bond\$3 adj pad)) and ((encapsulant encapsulating encapsulated encapsulation) sealing resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/24 09:59